

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3119274

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
GENERAL MEMS CORPORATION	08/25/2014
RECEIVING PARTY DATA	
Name:	NEOMEMS TECHNOLOGIES, INC., WUXI, CHINA
Street Address:	533 XISHAN AVENUE
Internal Address:	XISHAN ECONOMIC & TECHNOLOGICAL DEPARTMENT ZONE
City:	WUXI, JIANGSU PROVINCE
State/Country:	CHINA
Postal Code:	214106
PROPERTY NUMBERS Total: 6	
Property Type	Number
Patent Number:	8697470
Patent Number:	8571249
Patent Number:	8472648
Patent Number:	8325951
Patent Number:	7493821
Patent Number:	7152481
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	/HUANYONG GAO
SIGNATURE:	/Huanyong Gao/
DATE SIGNED:	11/21/2014
Total Attachments: 3	

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REEL: 034234 FRAME: 0965

PATENT ASSIGNMENT AGREEMENT

WHEREAS, GENERAL MEMS CORPORATION, having its principal place of business at 4051 Burton Dr, Santa Clara, CA 95054, USA, (hereinafter referred to as "ASSIGNOR"), owns the entire right, title and interest to and under certain inventions, patent applications and patents as set forth in Schedule 1; (collectively, the "Patents"); and

WHEREAS, NEOMEMS TECHNOLOGIES INC., WUXI, CHINA having its principal place of business at No.533,Xishan Avenue,Xishan Economic & Technological Development Zone,Wuxi,Jiangsu Province,China 214106 (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring the entire right, title and interest of ASSIGNOR in, to and under the Patents and in, to and under any patent or similar legal protection to be obtained therefor in the United States of America, its territorial possessions and in any and all countries foreign thereto.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR does hereby sell, assign, transfer and set over unto said ASSIGNEE, its successors and assigns, ASSIGNOR's entire right, title and interest to the Patents and to all Letters Patent or application or similar legal protection, not only in the United States and its territorial possessions, but in all countries foreign thereto, to be obtained by the Patents, and to any continuation, division, renewal, substitute or reissue thereof or any legal equivalent thereof in the United States or a foreign country for the full term or terms for which the same may be granted, including all priority rights under the International Convention; and ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents or any legal equivalent thereof, to issue said Letters Patent or any legal equivalent thereof to said ASSIGNEE, its successors and assigns, in accordance with this Agreement.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Agreement.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to the Patents and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce the Patents and said equivalents in the United States or in any foreign country, which may be necessary or desirable to carry out the purposes thereof.

GENERAL MEMS CORPORATION

By: Mark Wang
Name: MARK WANG
Title: CEO
Address: 4051 Burton Dr, Santa Clara, CA
95054, USA

SCHEDULE 1

PATENTS

Patent No.	App. No.	Pub. App. No	Subject Matter
8,697,470	13/644,449	20130059409	Miniature MEMS condenser microphone packages and fabrication method thereof
	13/170,151	20130028459	Monolithic Silicon Microphone
	13/169,065	20120328132	Perforated Miniature Silicon Microphone
8,571,249	12/786,723	20100303271	Silicon microphone package
8,472,648	12/816,730	20100246877	Miniature MEMS condenser microphone packages and fabrication method thereof
8,325,951	12/689,283	20100183181	Miniature MEMS condenser microphone packages and fabrication method thereof
	12/105,797		Capacitive micromachined acoustic transducer
	12/117,724	20080212807	Micromachined Acoustic Transducers
	11/644,501	20070113664	Capacitive micromachined acoustic transducer
	11/160,071	20060280319	Micromachined Capacitive Microphone
7,493,821	10/907,824	20060230835	Micromachined acoustic transducer and method of operating the same
7,152,481	10/907,706	20060233401	Capacitive micromachined acoustic transducer
6,945,115	10/708,448		Micromachined capacitive RF pressure sensor